ASSOCIATION CONNECTING	© Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	.ll rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat	ion of the su encompasse	ubstances v s all lower	within the manufactur level materials for w	rer listed in hich the m	em. Note: if anufacturer	the item is an as has engineering	ssembly with lower responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Inform	ation													
Company name*			Company unique ID				Unique ID Authority				Response Date*			
onsemi											2025-06-05			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative				Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requeste	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Version	Ν	Ianufacturing Site	· · · ·	Weight*	UOM	Unit Type
		NCV8413DTRKG LS Si		LS Smart FET MPW		2025-06-05		v	VN5		350.99	mg	Each	
Manufacturing]	Proccess Information	1												
Terminal Plating / Grid Array Material Terr			erminal Base A	minal Base Alloy J-STD-020 MSL R			Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alle			U Alloy	1	l		260		С	30	secon	ds 3		
Comments														
evel 1 - maximum ti	me at peak temperature o	luring sol	dering is 10-3	0 seconds										
For more information	on regarding material con	position j	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg	
Die Attach	1.4	mg	А	Lead (Pb)	7439-92-1	7a	1.33	mg	
			Supplier	Tin (Sn)	7440-31-5		0.07	mg	
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.0215	mg	
			Supplier	Iron (Fe)	7439-89-6		0.2146	mg	
			Supplier	Copper (Cu)	7440-50-8		214.3395	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.0644	mg	
Mold Compound-Black	129.65	mg		Epoxy resin	proprietary data		9.0755	mg	
			Supplier	Phenolic Resin	Proprietary Data		3.8895	mg	
			Supplier	Silica Amorphous (SiO2)	7631-86-9		12.965	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		103.0717	mg	
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg	
Wire Bond - Al	1.37	mg	Supplier	Aluminum (Al)	7429-90-5		1.37	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3